

24 V and 300 V DC-DC Converter Modules

Module Construction & Component Derating

This document provides a detailed view of the construction for Maxi, Mini and Micro DC-DC converters as well as the component design derating guidelines.



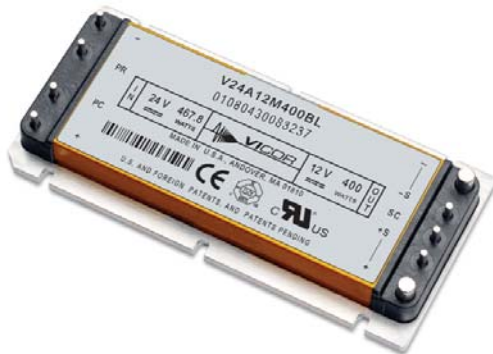
Module Size/Power Chart

Output Voltage	Maxi		Mini		Micro	
	24 Vin max. Output Power	300 Vin max. Output Power	24 Vin max. Output Power	300 Vin max. Output Power	24 Vin max. Output Power	300 Vin max. Output Power
2 V	N/A	160 W	N/A	100 W	N/A	50 W
3.3 V	264 W	264 W	150 W	150 W	75 W	75 W
5 V	400 W	400 W	200 W	200 W	100 W	100 W
12 V	400 W	500 W	200 W	250 W	100 W	150 W
15 V	400 W	500 W	200 W	250 W	100 W	150 W
24 V	400 W	500 W	200 W	250 W	100 W	150 W
28 V	400 W	500 W	200 W	250 W	100 W	150 W
36 V	400 W	500 W	200 W	250 W	100 W	150 W
48 V	400 W	500 W	200 W	250 W	100 W	150 W

Consult factory for other input / output / power modules.

Part Numbering

V	24	A	12	M	400	B	L	
Input Voltage		Package	Output Voltage	Product Grade	Output Power	Pin Style		Baseplate
		A = Maxi B = Mini C = Micro		E = -10 to +100°C C = -20 to +100°C T = -40 to +100°C H = -40 to +100°C M = -55 to +100°C		Blank = Short solder L = Long solder *S = Short ModuMate *N = Long ModuMate		Blank = Slotted 2 = Threaded 3 = Thru hole



Maxi converter example:

V24A12M400BL

24 Vin, Maxi, 12 V_{OUT} @ 400 W,
long solder pins, slotted baseplate



Mini converter example:

V300B28H250BL2

300 Vin, Mini, 28 V_{OUT} @ 250 W,
long solder pins, threaded baseplate



Micro converter example:

V24C5M100BL3

24 Vin, Micro, 5 V_{OUT} @ 100 W,
long solder pins, thru-hole baseplate

*Compatible with the InMate and SurfMate socketing systems.

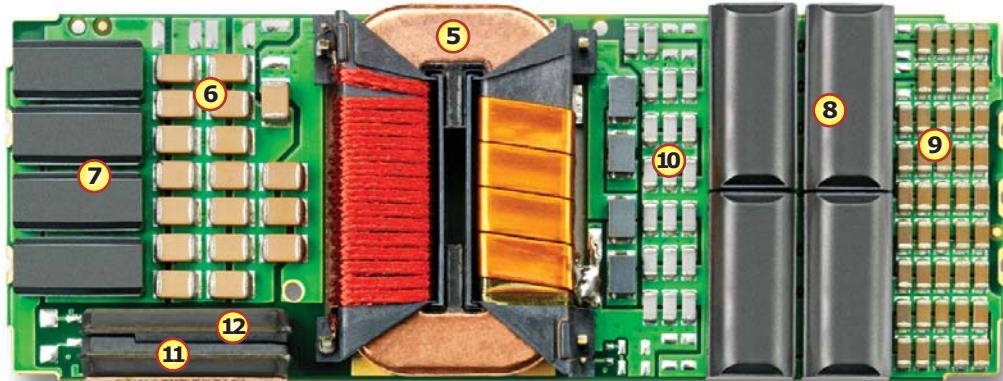
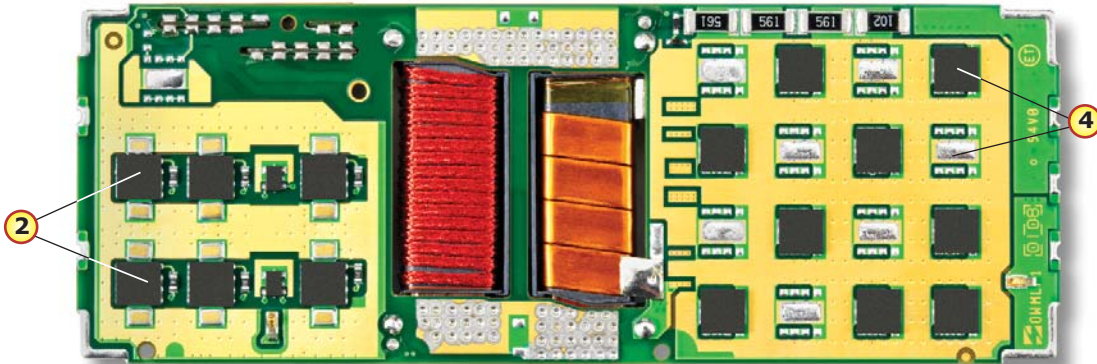
Qualification Testing

- ↻ **Acceleration** *To determine the ability of parts to withstand constant acceleration, as an indicator of the mechanical strength limits.*
Standard: MIL-STD-810F, Method 513.5, Procedure II • **Environment:** Acceleration step from 2 – 7 g, 6 direction
- ↻ **Altitude** *To observe low air pressure effects on either operational or non-operational design parameters.*
Standard: MIL-STD-810F, Method 500.4, Procedure I & II • **Environment:** 40,000 ft. and 70,000 ft. operational
- ↻ **Explosive Atmosphere** *To determine the ability of equipment to operate in the presence of an explosive atmosphere.*
Standard: MIL-STD-810F, Method 511.4, Procedure I, operational • **Environment:** Fuel-air explosive atmospheres
- ↻ **HALT** *Demonstrates product design margin and robustness.*
Standard: Vicor internal reference EIAJESD22-A110-B • **Environment:** Operational limits verified / destruct limits determined
- ↻ **High Temperature Operational Life** *An operational test used to detect thermally activated failure mechanisms.*
Standard: Vicor internal reference EIAJESD22-A110-B
Environment: Nominal line, 75% Load, temperature within 5°C max operational
- ↻ **Humidity** *A humidity test simulates the moisture-laden air found in tropical regions.*
Standard: MIL-STD-810F, Method 507.4 • **Environment:** 240 hours, 95% RH
- ↻ **Mechanical Shock** *To determine the ability to withstand mechanical shocks from suddenly applied forces or an abrupt change in motion produced by handling, transportation or field operation.*
Standard: MIL-STD-810F, Method 516.5, Procedure I • **Environment:** Functional shock, 40 g
Standard: MIL-S-901D, lightweight hammer shock • **Environment:** 3 impacts/axis, 1, 3, 5 ft.
Standard: MIL-STD-202F, Method 213B • **Environment:** 60 g, 9 ms half sine; 75 g, 11 ms saw tooth shock.
- ↻ **Random Mechanical Vibration** *To evaluate the construction, materials and mounting of the device for ruggedness.*
Standard: MIL-STD-810F, Method 514.5, Procedure I, Category 14 • **Environment:** Sine and random vibration for helicopter AH-6J main rotor with overall level of 5.6 g for 4 hours per axis
Standard: MIL-STD-810F, Method 514.5C, general minimum integrity • **Environment:** 7.7 g for 1 hour per axis.
- ↻ **Resistance to Solvents** *To verify that component markings will not become illegible and that electrical and mechanical integrity will not be disturbed when exposed to solvents.*
Standard: MIL-STD-202G, Method 215K • **Environment:** Ambient temperature, ambient humidity
- ↻ **Temperature Humidity Bias** *An operational test that evaluates the reliability of the device package in humid environments.*
Standard: JESD22-A101-B • **Environment:** 85°C, 85% RH, high line input voltage
- ↻ **Thermal Shock** *To determine the resistance of the part to sudden changes in temperature.*
Standard: MIL-STD-202G, Method 107G, Condition B1 and MIL-HDBK-344A • **Environment:** -65°C to 125°C, 1,000 cycles
- ↻ **Temperature Cycle** *Conducted to determine the ability of devices to withstand mechanical stresses induced by alternating high and low temperature extremes.*
Standard: JESD22-A104-B • **Environment:** -40°C to 125°C, 1,000 cycles

Characterization Process

- ↻ **Electro Static Discharge** *Classifies the device according to its susceptibility to damage or degradation by exposure to electrostatic discharge.*
Standard: MIL-STD-883C, Method 3015 • **Environment:** Ambient temperature, ambient humidity
- ↻ **Fungus** *To determine if a material(s) will support the growth of specific fungi.*
Standard: MIL-STD-810F, Method 508.5 • **Environment:** Severe climate conditions
- ↻ **Salt Fog** *To determine the resistance of the equipment to the effects of a salt atmosphere, primarily corrosion.*
Standard: MIL-STD-810F, Method 509.4 • **Environment:** Salt fog harsh environment
- ↻ **Solderability** *To evaluate the solderability of terminations that are normally joined by a soldering operation.*
Standard: MIL-STD-202G, Method 208H • **Environment:** Continuous solder coating for a minimum of 95% surface area
- ↻ **Terminal Strength** *Determines the resistance to external force on the terminals.*
Standard: MIL-STD-202G, Method 211A, Test Condition A • **Environment:** Ambient temperature, ambient humidity
- ↻ **AMCOM Testing** *Developed in partnership with the U.S. Army Aviation and Missile Command to demonstrate the ability to withstand sequential harsh environments, which simulate storage, field use and a 10 year service life in a ground mobile environment.*
Standard: US Army Aviation and Missile Command • **Environment:** High temp / high humidity, temp cycle, power cycle

MAXI



2.2"
55,9 mm



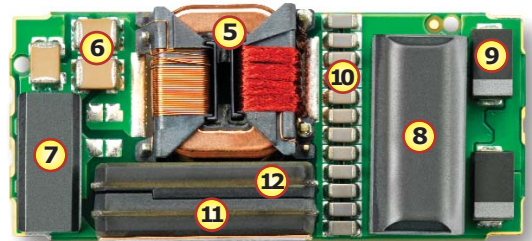
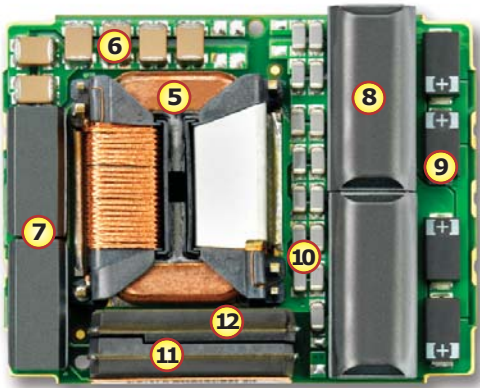
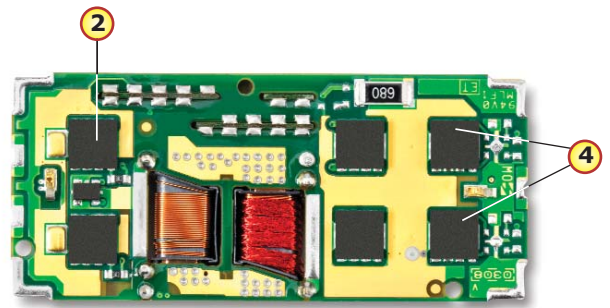
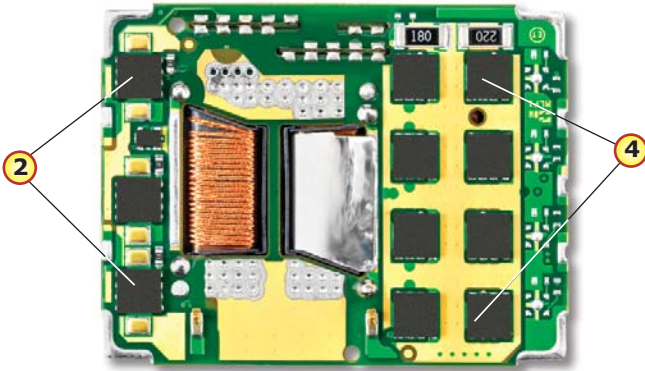
4.6"
116,8 mm

0.5"
12,7 mm



MINI

MICRO

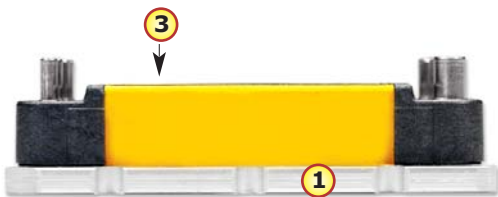


1.45"
36,8 mm



2.28"
57,9 mm

2.28"
57,9 mm



Component

24 V Input

The photos to the left illustrate typical Maxi, Mini and Micro DC-DC converters and the captions below provide information as to materials and operating parameters. Temperatures and voltages shown are for nominal input voltages under full load conditions at 100°C baseplate; maximum device ratings are shown in parenthesis.

		24 Vout Maxi V24A24M400BL	5 Vout Mini V24B5H200BL
1 Baseplate	Provides mounting, mechanical rigidity and heat spreading.	Aluminum 6063T-5	Aluminum 6063T-5
2 Mosfet MLP	Main switch and common drain for low conducted and radiated noise	Quantity: 6 121°C (150°C) 37 V (60 V) $\theta_j = 10^\circ\text{C/W}$	Quantity: 3 126°C (150°C) 35 V (60 V) $\theta_j = 10^\circ\text{C/W}$
3 Insert Molded Terminal Block and Shield	Functions as an EMI shield to reduce conducted and radiated noise, supplies electrical isolation for the pins and provides mechanical protection for the module.	DuPont Zenite/ Clad Aluminum	DuPont Zenite/ Clad Aluminum
4 Rectifier MLP	A dual diode rectifier	Quantity: 4 (forward) + 8 (shunt) Forward: 117°C (150°C) 87 V (200 V) Shunt: 105°C (150°C) 87 V (200 V) $\theta_j = 10^\circ\text{C/W}$	Quantity: 4 (forward) + 4 (shunt) Forward: 121°C (150°C) 21 V (45 V) Shunt: 115°C (150°C) 21 V (45 V) $\theta_j = 10^\circ\text{C/W}$
5 Main Transformer	Provides voltage transformation and primary to secondary isolation.	110°C (180°C) core	116°C (180°C) core
6 Input Capacitor	Reduces reflected ripple and conducted noise in conjunction with the input inductor.	Quantity: 42 24 V (50 V)	Quantity: 14 24 V (50 V)
7 Input Inductor	Reduces reflected ripple and conducted noise in conjunction with the input capacitors.	Quantity: 4 101°C (180°C) core	Quantity: 1 104°C (180°C) core
8 Output Inductor	Reduces output ripple in conjunction with the output capacitors.	Quantity: 4 102°C (180°C) core	Quantity: 2 117°C (180°C) core
9 Output Capacitor	Reduces output ripple in conjunction with the output inductor.	Quantity: 43 24 V (50 V)	Quantity: 4 5 V (10 V)
10 Resonant Capacitor	Quasi-resonant tank for zero-current-switching converter	Quantity: 20 87 V (250 V)	Quantity: 10 21 V (50 V)
11 Brain (primary)	Contains primary control device (ASIC).	102°C (135°C)	108°C (135°C)
12 Brain (secondary)	Contains secondary control device (ASIC).	102°C (135°C)	108°C (135°C)
Encapsulant	Two component silicone elastomer		Thermal conductivity: 3.2 W/m-k Temperature rating guide: 200°C
MTBF	MIL-HDBK-217F: G.B. @ 25°C Baseplate MTBF in 1000 hours	2210	4205
PRISM	PRISM ties together several tools into a comprehensive system reliability prediction methodology that accounts for the myriad of factors that can influence reliability.	0.091808	0.056142

300 V Input

15 Vout Micro V24C15M100BL	24 Vout Maxi V300A24H500BL	5 Vout Mini V300B5M200BL	15 Vout Micro V300C15H150BL
Aluminum 6063T-5	Aluminum 6063T-5	Aluminum 6063T-5	Aluminum 6063T-5
Quantity: 2 111°C (150°C) 33 V (60 V) $\theta_j = 10^\circ\text{C/W}$	Quantity: 6 119°C (150°C) 484 V (550 V) $\theta_j = 10^\circ\text{C/W}$	Quantity: 3 120°C (150°C) 404 V (650 V) $\theta_j = 10^\circ\text{C/W}$	Quantity: 2 129°C (150°C) 406 V (650 V) $\theta_j = 10^\circ\text{C/W}$
DuPont Zenite/ Clad Aluminum	DuPont Zenite/ Clad Aluminum	DuPont Zenite/ Clad Aluminum	DuPont Zenite/ Clad Aluminum
Quantity: 2 (forward) + 2 (shunt) Forward: 104°C (150°C) 57 V (100 V) Shunt: 104°C (150°C) 57 V (100 V) $\theta_j = 10^\circ\text{C/W}$	Quantity: 8 (forward) + 8 (shunt) Forward: 106°C (150°C) 135 V (200 V) Shunt: 110°C (150°C) 135 V (200 V) $\theta_j = 10^\circ\text{C/W}$	Quantity: 4 (forward) + 4 (shunt) Forward: 116°C (150°C) 24 V (30 V) Shunt: 115°C (150°C) 24 V (30 V) $\theta_j = 10^\circ\text{C/W}$	Quantity: 2 (forward) + 2 (shunt) Forward: 112°C (150°C) 71 V (100 V) Shunt: 112°C (150°C) 71 V (100 V) $\theta_j = 10^\circ\text{C/W}$
107°C (180°C) core	119°C (180°C) core	119°C (180°C) core	127°C (180°C) core
Quantity: 8 24 V (50 V)	Quantity: 18 300 V (600 V)	Quantity: 6 300 V (600 V)	Quantity: 3 300 V (600 V)
Quantity: 1 101°C (180°C) core	Quantity: 4 103°C (180°C) core	Quantity: 2 107°C (180°C) core	Quantity: 1 113°C (180°C) core
Quantity: 1 103°C (180°C) core	Quantity: 4 110°C (180°C) core	Quantity: 2 125°C (180°C) core	Quantity: 1 112°C (180°C) core
Quantity: 2 15 V (25 V)	Quantity: 43 24 V (50 V)	Quantity: 4 5 V (10 V)	Quantity: 2 15 V (25 V)
Quantity: 7 57 V (100 V)	Quantity: 20 135 V (250 V)	Quantity: 15 24 V (50 V)	Quantity: 12 71 V (100 V)
102°C (135°C)	109°C (135°C)	118°C (135°C)	114°C (135°C)
102°C (135°C)	109°C (135°C)	118°C (135°C)	114°C (135°C)
		Thermal conductivity: 3.2 W/m-k Temperature rating guide: 200°C	
4646	2690	5324	6104
0.043105	0.094210	0.047520	0.067441



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